Tuya Smart

Tuya Smart Zigbee Module

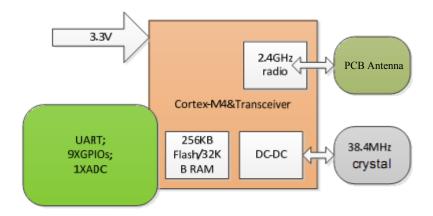
1. Product Overview

TYZS2 is a low power consumption module with built-in Zigbee connectivity TYZS2 solution designed by Hangzhou Tuya Information Technology Co., Ltd. The Zigbee Module consists of a highly integrated wireless radio chip EFR32MG1B132 and some extra component that has been programed with Zigbee network protocol 802.15.4 PHY/MAC and plenty of software examples. TYZS2 include a 32-bit ARM Cortex-M4 CPU, 256K byte flash, 32k SRAM and various peripheral resources.

TYZS2 is a Free RTOS platform, embedded with all the Zigbee MAC and TCP/IP protocol function examples, users can customize their Zigbee product by using these software examples.

Figure 1 shows the block diagram of the TYZS2.

Figure 1. The block diagram of the TYZS2



1.1 Features

- ♦ Integrated low power consumption 32-bit ARM Cortex-M4 CPU, with DSP command and float computing unit also using for application processor
- ♦ Basic frequency of the CPU can support 40MHz
- ♦ Supply voltage range: 1.8V to 3.8V
- ♦ Peripherals: 6 GPIO channels, 1 UART, 1 ADC
- - 802.15.4 MAC/PHY
 - Channel 11 to 26 @ 2.400-2.480 GHz, radio rate 250 kbps
 - Embedded DC-DC circuit, maximally improving power efficiency
 - +9.15dBm output power
 - 1.4uA standby current at 63uA/MHz
 - Automatic paring for terminals

- On-board PCB antenna
- Operating temperature range: -40°C to 85°C
- Hardware encryption, AES 128/256

1.2 Main Application Fields

- ♦ Intelligent Building
- ♦ Intelligent home, Intelligent household applications
- ♦ Smart socket, smart lighting
- ♦ Industrial wireless control
- ♦ Health and measurement management
- ♦ Asset trace

2. Dimensions and Footprint

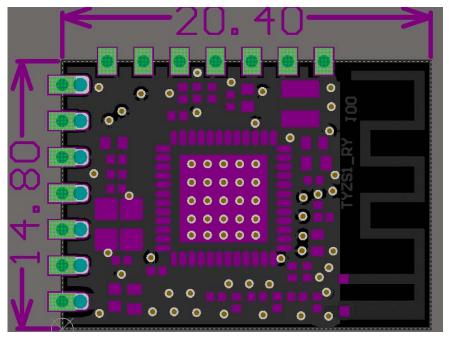
2.1 Dimensions

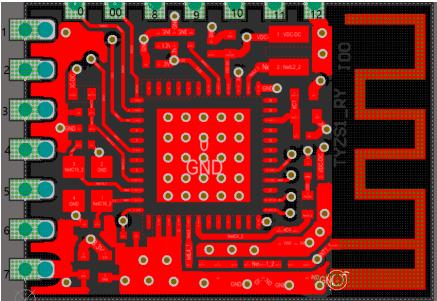
TYZS2 has 2 columns of Pins. The distance between each Pin is 2mm.

Size of TYZS2: 14.8mm(W)*20.4mm(L)*2mm(H)

Figure 2 shows the dimensions of TYZS2.

Figure 2. The dimensions of TYZS2





2.2 Pin Definition

Table 1 shows the general pin attributes of TYZS2

Table 1. The typical pin definition of TYZS2

PIN NO.	PIN NO. NAME TYPE DISCREPTION					
1	PWM1	1/0	used for LED driver output / universal GPIO			
2	PWM2	1/0	used for LED driver output / universal GPIO			
3	I2C_SDA	1/0	I2C_SDA, also can be used as universal GPIO			
4	I2C_SCL	1/0	I2C_SCL, also can be used as universal GPIO			
5	VCC	P	Supply voltage (3.3V)			
6	ADC	Al	ADC terminal(12-bits SAR ADC)			
7	GND	Р	Ground			
0	SWDIO	I/O	JLINK SWDIO buring pin, also used for universal GPIO			
0	SWCLK	1/0	JLINK SWCLK buring pin, also used for universal GPIO			
8	RXD	1/0	UARTO_RXD			
9	nRST	ı	hardware reset pin, low level effects;			
			the module will reset while booting, user could ignore the			
			pin just in case			
10	VCC	Р	Supply voltage (3.3V)			
11	TXD	0	UARTO_TXD			
12	GND	Р	Ground			

Note: S: Power supply pins; I/O: Digital input or output pins; AI: Analog input. RST pin is the module hardware reset pin; it cannot eliminate Zigbee module pairing information.

(1) This pin can only be used as ADC input, cannot use it as normal I/O. when not using, just connect nothing. When used as ADC input, the input voltage range is 0~AVDD, can be configured by firmware.

2.3 Test Pin Definition

Table 2 shows the general test pin definition of TYZS2

Table 2. The general test pin definition of TYZS2

PIN NO.	SYMBOL	TYPE	DESCRIPTION	
-	TEST	1	Used for module's production test	

Note: This test pin is not recommended to use.

3. Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 3. Absolute Maximum Ratings

PARAMETERS	DESCRIPTION	MIN	MAX	UNIT
Ts	Storage temperature	-50	150	$^{\circ}$ C
VCC	Supply voltage	-0.3	3.8	V
Static electricity voltage	TAMB-25℃	-	2.5	KV
(human model)				
Static electricity voltage	TAMB-25℃	-	0.5	KV
(machine model)				

3.2 Electrical Conditions

Table 4. Electrical Conditions

PARAMETERS	DESCRIPTION	MIN	TYPICAL	MAX	UNIT
Та	Working temperature	-40	-	85	$^{\circ}\!\mathbb{C}$
VCC	Working voltage	1.8	3.3	3.8	V
VIL	IO low level input	-0.3	-	VCC*0.25	V
VIH	IO high level input	VCC*0.75	-	VCC	V
VOL	IO low level output	-	-	VCC*0.1	V
VoH	IO high level output	VCC*0.8	-	VCC	V
Imax	IO drive current	-	-	12	mA

3.3 Zigbee Transmitting Current Consumptions

Table 5. Zigbee TX current consumption

PARAMETERS	RATE	Transmitting power	TYPICAL	UNIT
IRF	250kbps	+9.15dBm	32	mA
IRF	250kbps	+9.10dBm	17	mA
IRF	250kbps	+6.29dBm	11.8	mA

Note: continuously transmitting data while testing the result shown above, duty cycle=100%

3.4 Zigbee Receiving Current Consumptions

Table 6. Zigbee RX current consumption

PARAMETERS	RATE	TYPICAL	UNIT
IRF	250kbps	8	mA

Note: Receiving current 14mA while in active mode.

3.5 Working Mode Current Consumptions

Table 7. The module working current consumption

WORK MODE	AT TA=25℃	TYPICAL	MAX*	UNIT
Quick pairing	TYZS2 is under quick paring mode with	10	40	mA
Mode	Gateway			
Connection	TYZS2 is connected	0.005	1	mA
Mode				
Deep sleep	TYZS2 is in deep sleep mode, reserving 64KB	1.4	3	uA
Mode	flash			

4. WLAN Radio Specification

4.1 Basic Radio Frequency Characteristics

Table 8. Basic Radio frequency characteristics

PARAMETERS	DESCRIPTION	
Frequency band	2.405GHz to 2.480GHz	
Zigbee standard	IEEE 802.15.4	
Data transmitting rate	250kbps	
Antenna type	On-board PCB Antenna	
Visible transmitting distance	>100m	

4.2 Zigbee Transmitting Power

Table 9. Zigbee transmitting power

PARAMETERS	MIN	TYPICAL	MAX	UNI
				T
Maximum output power	-	9.15	ı	dBm
Minimum output power	-	6.29	ı	dBm
The Frequency error	-15	-	+15	ppm
Output frequency adjacent channel suppression		-31		dBc

4.3 Zigbee Receiving Sensitivity

Table 9. Zigbee Receiving sensitivity

PARAMETERS	MIN	TYPICAL	MAX	UNIT
PER<10%, Receiving sensitivity, 250kbps @ OQPSK	-	-102	-	dBm

5. Antenna Information

5.1 Antenna Type

Antenna can be default connected using On-board PCB antenna.

5.2 Reduce Antenna Interference

While using the On-board PCB antenna, in order to have the best Zigbee performance, it's recommended to keep a minimum 15mm distance between the antenna part and the other metal pieces.

User's own PCBA design is recommended NOT to pass any wire, NOT do copper pour under the region of the module's antenna, to avoid interferences.

6. Packaging Information And Production Guide

6.1 Mechanical Dimensions

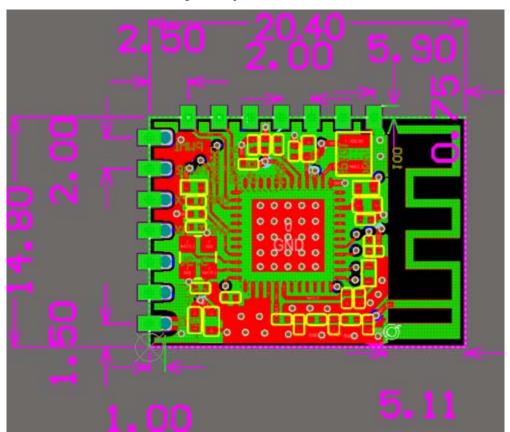


Figure 3. Top view of the module

6.2 PCB Recommended Package

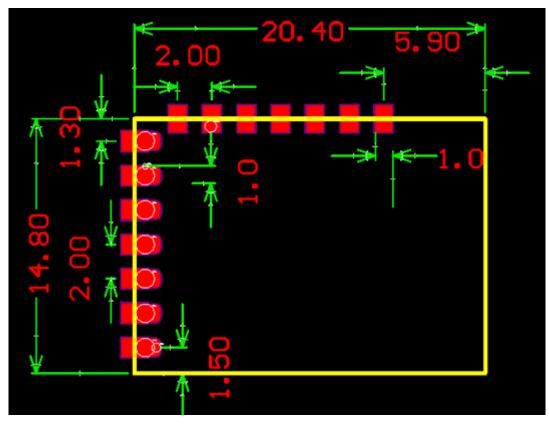


Figure 4. PCB Package Drawing

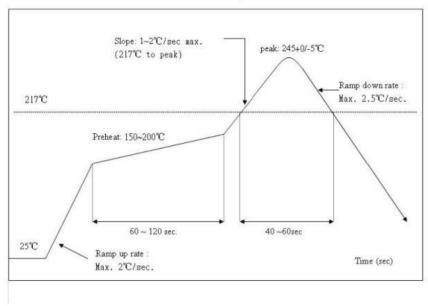
6.3 Production Guide

- ♦ The storage for the delivered module should meet the following condition:
- 1. The anti-moisture bag should be kept in the environment with temperature $< 30\,^{\circ}\text{C}$ and humidity < 85% RH.
 - 2. The expiration date is 6 months since the dry packaging products was sealed.
- ♦ Cautions:
 - 1. All the operators should wear electrostatic ring in the whole process of production.
 - 2. While operating, water and dirt should not have any contact with the modules.

6.4 Recommended furnace temperature curve

Figure 5. PCB Package Drawing Recommended furnace temperature curve





FCC Statement:

Any Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) This device must accept any interference received, including interference that may cause undesired operation.

FCC Radiation Exposure Statement:

This equipment complies with FCC radiation exposure limits set forth for an uncontrolled environment .This equipment should be installed and operated with minimum distance 20cm between the radiator& your body.

FCC Label Instructions:

The outside of final products that contains this module device must display a label referring to the enclosed module. This exterior label can use wording such as: "Contains Transmitter Module FCC ID:2ANDL-TYZS2", or "Contains FCC ID:2ANDL-TYZS2", Any similar wording that expresses the same meaning may be used.